

# **FQA34N25**

### 250V N-Channel MOSFET

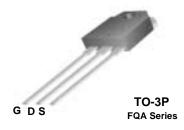
#### **General Description**

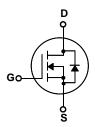
These N-Channel enhancement mode power field effect transistors are produced using Fairchild's proprietary, planar, DMOS technology.

This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency switching DC/DC converters and switch mode power supplies.

#### **Features**

- 34A, 250V,  $R_{DS(on)}$  = 0.085 $\Omega$  @V<sub>GS</sub> = 10 V Low gate charge ( typical 60 nC)
- Low Crss (typical 60 pF)
- Fast switching
- 100% avalanche tested
- · Improved dv/dt capability





## Absolute Maximum Ratings T<sub>C</sub> = 25°C unless otherwise noted

Symbol	Parameter		FQA34N25	Units
$V_{DSS}$	Drain-Source Voltage		250	V
I <sub>D</sub>	Drain Current - Continuous (T <sub>C</sub> = 25°	C)	34	Α
	- Continuous (T <sub>C</sub> = 100	°C)	21.3	Α
I <sub>DM</sub>	Drain Current - Pulsed	(Note 1)	136	Α
$V_{GSS}$	Gate-Source Voltage		± 30	V
E <sub>AS</sub>	Single Pulsed Avalanche Energy	(Note 2)	700	mJ
I <sub>AR</sub>	Avalanche Current	(Note 1)	34	А
E <sub>AR</sub>	Repetitive Avalanche Energy	(Note 1)	24.5	mJ
dv/dt	Peak Diode Recovery dv/dt	(Note 3)	4.8	V/ns
P <sub>D</sub>	Power Dissipation (T <sub>C</sub> = 25°C) - Derate above 25°C		245	W
			1.96	W/°C
T <sub>J</sub> , T <sub>STG</sub>	Operating and Storage Temperature Range		-55 to +150	°C
T <sub>L</sub>	Maximum lead temperature for soldering purposes, 1/8" from case for 5 seconds		300	°C

## **Thermal Characteristics**

Symbol	Parameter	Тур	Max	Units
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case		0.51	°C/W
$R_{\theta CS}$	Thermal Resistance, Case-to-Sink	0.24		°C/W
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient		40	°C/W

Symbol	Parameter	Test Conditions		Min	Тур	Max	Units
Off Cha	aracteristics						
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$		250			V
ΔBV <sub>DSS</sub> / ΔΤ <sub>J</sub>	Breakdown Voltage Temperature Coefficient	I <sub>D</sub> = 250 μA, Referenced to	I <sub>D</sub> = 250 μA, Referenced to 25°C		0.27		V/°C
I <sub>DSS</sub>	7 0 . 1/1 5 . 0	V <sub>DS</sub> = 250 V, V <sub>GS</sub> = 0 V				10	μΑ
	Zero Gate Voltage Drain Current	V <sub>DS</sub> = 200 V, T <sub>C</sub> = 125°C				100	μΑ
I <sub>GSSF</sub>	Gate-Body Leakage Current, Forward	V <sub>GS</sub> = 30 V, V <sub>DS</sub> = 0 V				100	nA
I <sub>GSSR</sub>	Gate-Body Leakage Current, Reverse	$V_{GS} = -30 \text{ V}, V_{DS} = 0 \text{ V}$				-100	nA
On Cha	racteristics						
V <sub>GS(th)</sub>	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_{D} = 250 \mu\text{A}$		3.0		5.0	V
R <sub>DS(on)</sub>	Static Drain-Source On-Resistance	$V_{GS} = 10 \text{ V}, I_D = 17 \text{ A}$			0.067	0.085	Ω
9 <sub>FS</sub>	Forward Transconductance	V <sub>DS</sub> = 40 V, I <sub>D</sub> = 17 A	(Note 4)		24		S
C <sub>iss</sub> C <sub>oss</sub> C <sub>rss</sub>	Input Capacitance Output Capacitance Reverse Transfer Capacitance	$V_{DS} = 25 \text{ V}, V_{GS} = 0 \text{ V},$ f = 1.0  MHz			465 60	610 80	pF pF
C <sub>rss</sub>	Reverse Transfer Capacitance				60	80	p⊦
Switchi	ng Characteristics	1					
t <sub>d(on)</sub>	Turn-On Delay Time	V <sub>DD</sub> = 125 V, I <sub>D</sub> = 34 A,	$V_{DD} = 125 \text{ V}, I_D = 34 \text{ A},$		45	100	ns
t <sub>r</sub>	Turn-On Rise Time	$R_G = 25 \Omega$			335	680	ns
t <sub>d(off)</sub>	Turn-Off Delay Time		Note 4, 5)		110	230	ns
t <sub>f</sub>	Turn-Off Fall Time	(1	Note 4, 5)		150	310	ns
Qg	Total Gate Charge	$V_{DS} = 200 \text{ V}, I_{D} = 34 \text{ A},$			60	80	nC
Q <sub>gs</sub>	Gate-Source Charge	V <sub>GS</sub> = 10 V			14		nC
Q <sub>gd</sub>	Gate-Drain Charge	(1	Note 4, 5)		36		nC
Drain-S	Source Diode Characteristics a	nd Maximum Ratings					
I <sub>S</sub>	Maximum Continuous Drain-Source Diode Forward Current				34	Α	
I <sub>SM</sub>	Maximum Pulsed Drain-Source Diode I	orward Current				136	Α
V <sub>SD</sub>	Drain-Source Diode Forward Voltage	$V_{GS} = 0 \text{ V}, I_{S} = 34 \text{ A}$				1.5	V
t <sub>rr</sub>	Reverse Recovery Time	$V_{GS} = 0 \text{ V}, I_{S} = 34 \text{ A},$			220		ns
Q <sub>rr</sub>	Reverse Recovery Charge	$dI_F / dt = 100 \text{ A/}\mu\text{s}$ (Note 4)			1.9		μС

- $\label{eq:Notes:Notes:} \textbf{Notes:} \\ 1. \ \text{Repetitive Rating}: \ \text{Pulse width limited by maximum junction temperature} \\ 2. \ L = 0.97 \text{mH}, \ I_{AS} = 34 \text{A}, \ V_{DD} = 50 \text{V}, \ R_G = 25 \ \Omega, \ \text{Starting} \ \ T_J = 25 ^{\circ} \text{C} \\ 3. \ I_{SD} \leq 14 \text{A}, \ di/dt \leq 300 \text{A}/\mu\text{s}, \ V_{DD} \leq B V_{DSS}, \ \text{Starting} \ \ T_J = 25 ^{\circ} \text{C} \\ 4. \ \text{Pulse Test}: \ \text{Pulse width} \leq 300 \mu\text{s}, \ \text{Duty cycle} \leq 2\% \\ 5. \ \text{Essentially independent of operating temperature} \\ \end{aligned}$

# **Typical Characteristics**

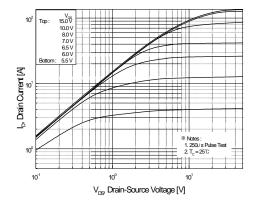


Figure 1. On-Region Characteristics.

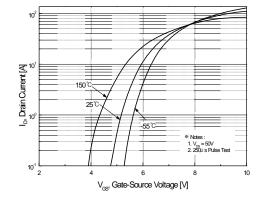


Figure 2. Transfer Characteristics.

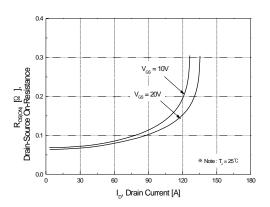


Figure 3. On-Resistance Variation vs Drain Current and Gate Voltage.

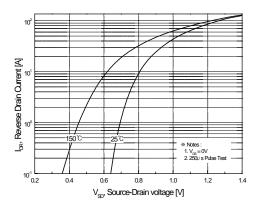


Figure 4. Body Diode Forward Voltage Variation with Source Current and Temperature.

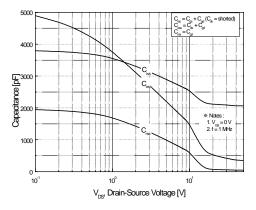


Figure 5. Capacitance Characteristics.

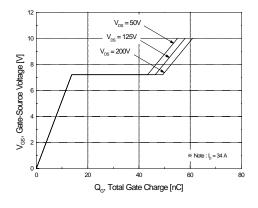


Figure 6. Gate -Charge Characteristics.

## Typical Characteristics (Continued)

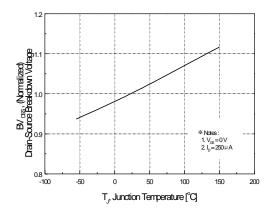


Figure 7. Breakdown Voltage Variation vs Temperature.

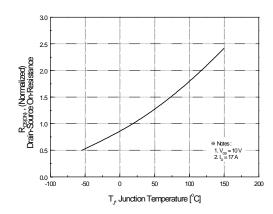


Figure 8. On-Resistance Variation vs Temperature.

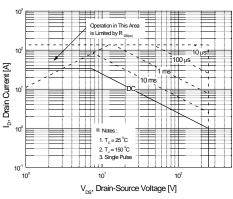


Figure 9. Maximum Safe Operating Area.

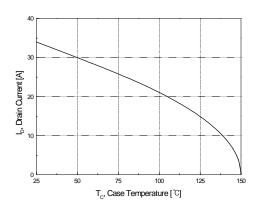


Figure 10. Maximum Drain Current vs Case Temperature.

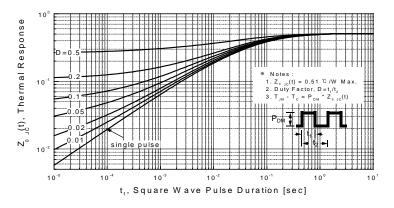
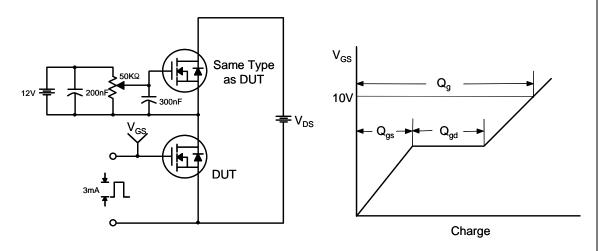


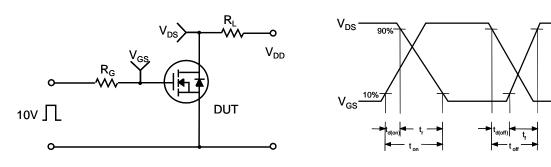
Figure 11. Transient Thermal Response Curve.

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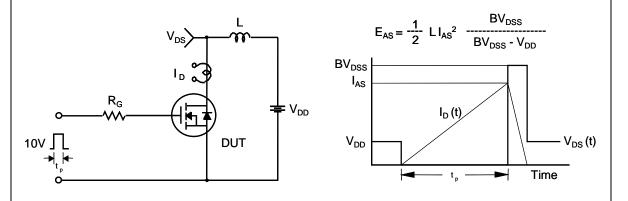
## **Gate Charge Test Circuit & Waveform**



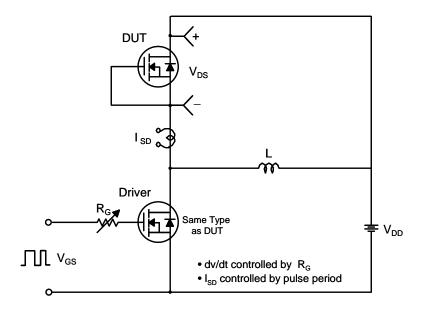
### **Resistive Switching Test Circuit & Waveforms**

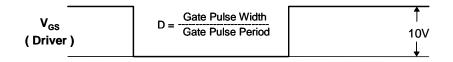


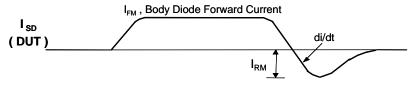
## **Unclamped Inductive Switching Test Circuit & Waveforms**



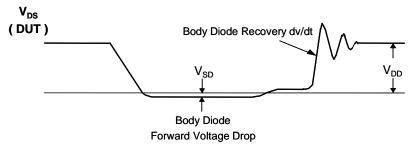
#### Peak Diode Recovery dv/dt Test Circuit & Waveforms

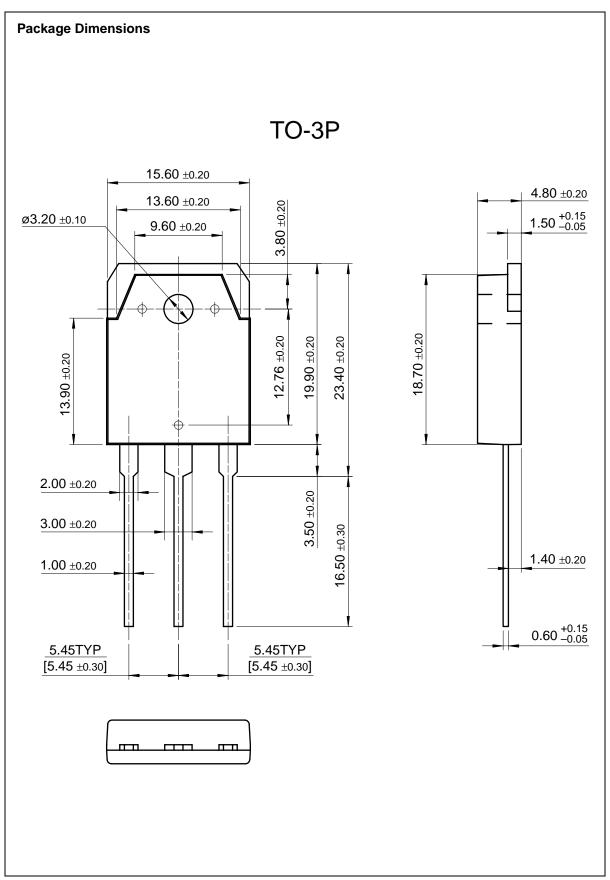






Body Diode Reverse Current





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